



GP
ELECTRONICS

GPM075N04LTF
40V N-Channel MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	6.5mΩ@10V	55A
	8.2mΩ@4.5V	

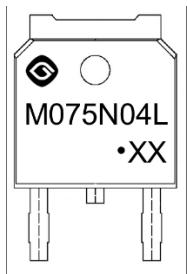
Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance
- 100% UIS Tested

Application

- Power Switching Application

MARKING:

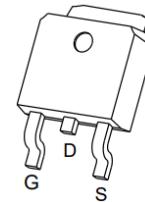


M075N04L = Device Code

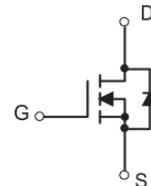
XX = Date Code

Solid Dot = Green Indicator

TO-252-2L



Schematic diagram



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

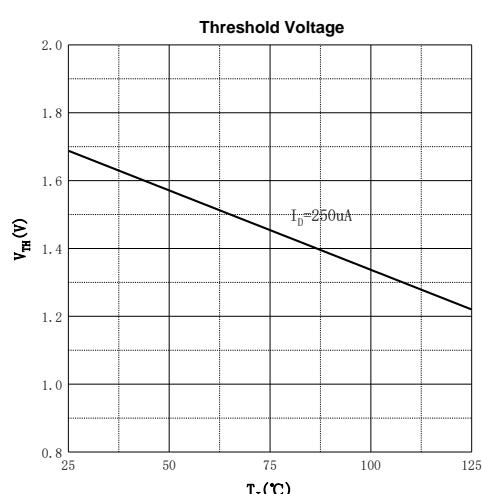
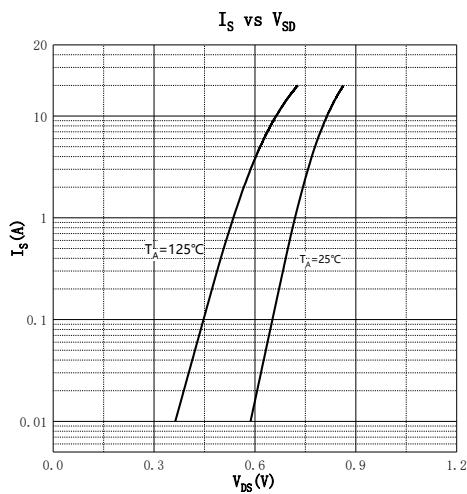
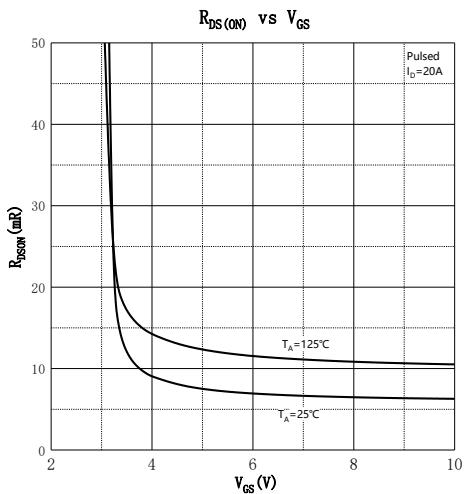
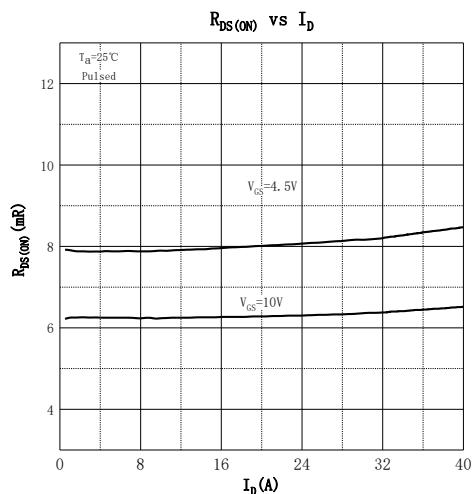
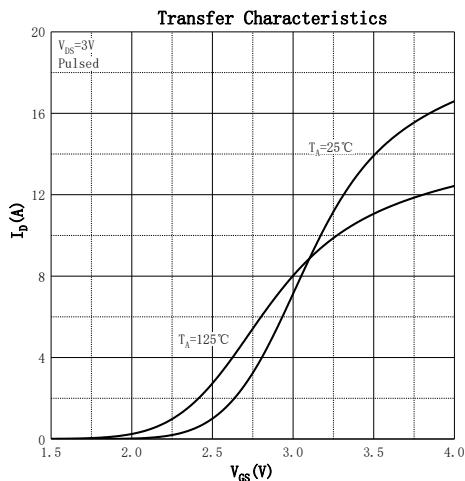
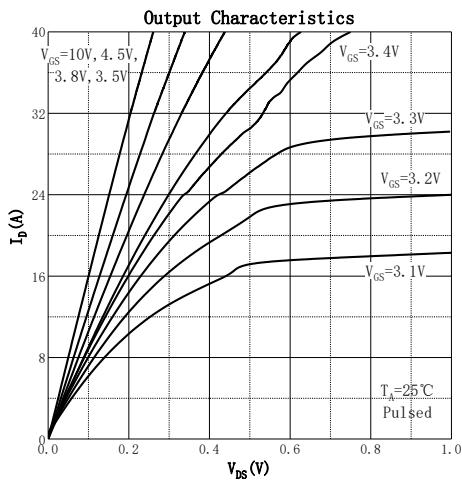
Parameter	Symbol	Value	Unit
Drain - Source Voltage	V_{DS}	40	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	55	A
	I_D	41	A
Pulsed Drain Current ²	I_{DM}	220	A
Single Pulsed Avalanche Current ³	I_{AS}	27	A
Single Pulsed Avalanche Energy ³	E_{AS}	182	mJ
Power Dissipation ⁵	P_D	41.5	W
Thermal Resistance from Junction to Ambient ⁶	$R_{\theta JA}$	55	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	3	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

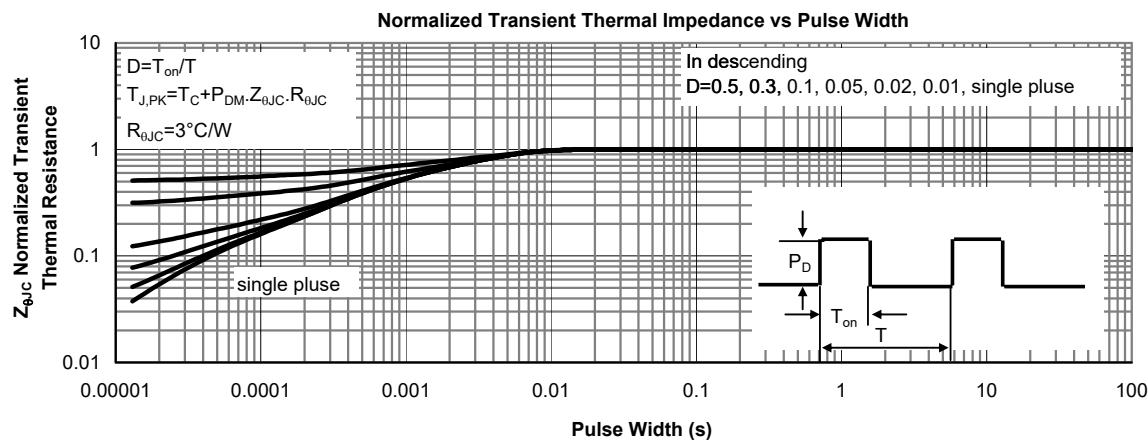
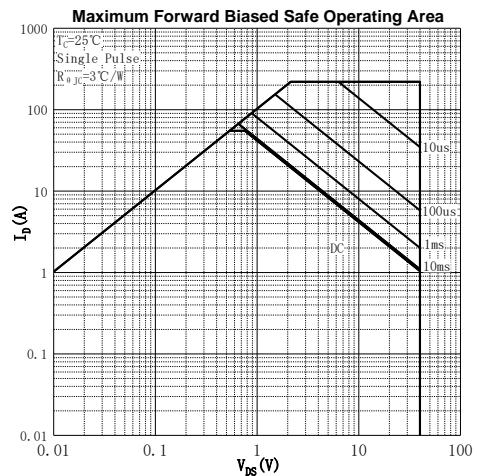
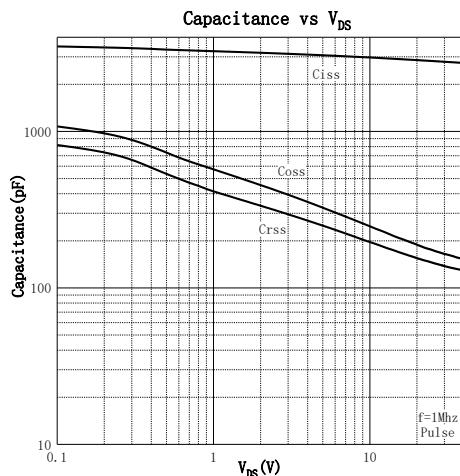
MOSFET ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			± 100	nA
On Characteristics⁴						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.7	3	V
Drain-source On-resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		6.5	8.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 10\text{A}$		8.2	12	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 10\text{A}$				S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2896		pF
Output Capacitance	C_{oss}			190		
Reverse Transfer Capacitance	C_{rss}			157		
Gate Resistance	R_g	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		2		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		51		nC
Gate-source Charge	Q_{gs}			9		
Gate-drain Charge	Q_{gd}			7.7		
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, V_{\text{GS}} = 10\text{V}, R_L = 1.5\Omega$ $R_G = 3\Omega$		9		ns
Turn-on Rise Time	t_r			22		
Turn-off Delay Ttime	$t_{\text{d}(\text{off})}$			45		
Turn-off Fall Time	t_f			22		
Source - Drain Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_s = 10\text{A}$			1.2	V

Notes :

- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu\text{s}$, duty cycle $\leq 1\%$.
- 3.E_{AS} condition: $V_{\text{DD}} = 20\text{V}, V_{\text{GS}} = 10\text{V}, L = 0.5\text{mH}, R_G = 25\Omega$ Starting $T_J = 25^\circ\text{C}$.
- 4.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(\text{MAX})} = 150^\circ\text{C}$.And device mounted on a large heatsink
- 6.Device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Characteristics




TO-252-2L Package Information
